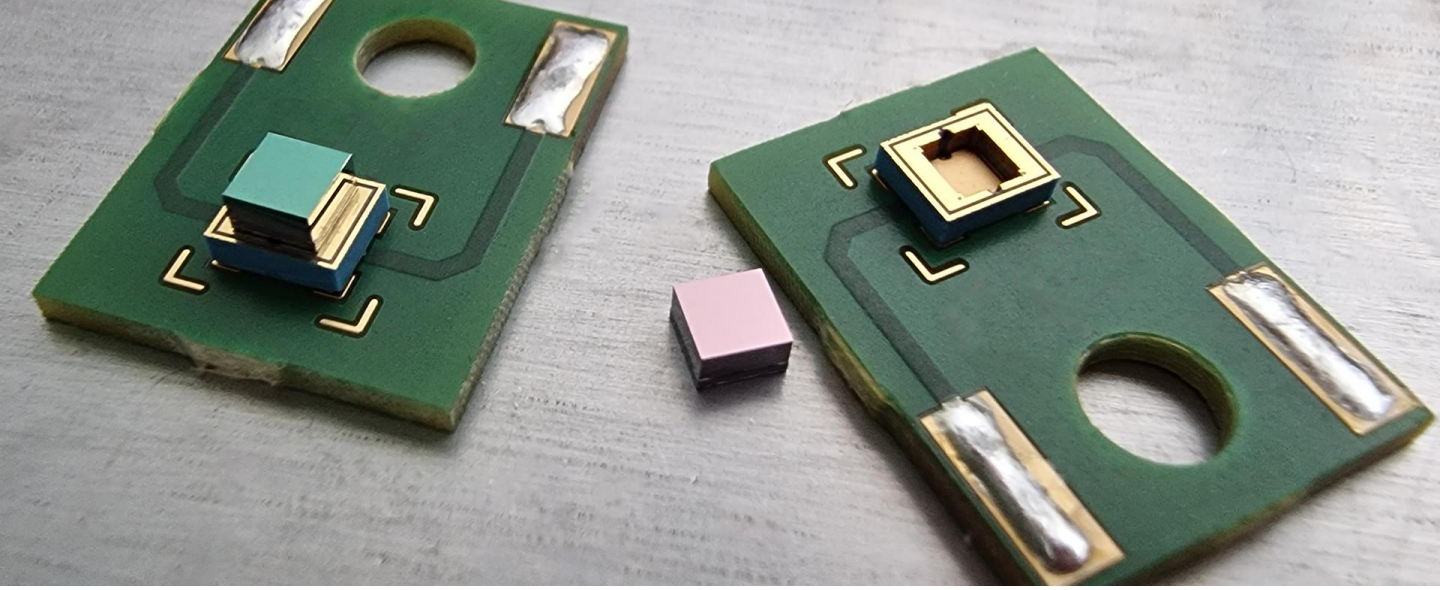


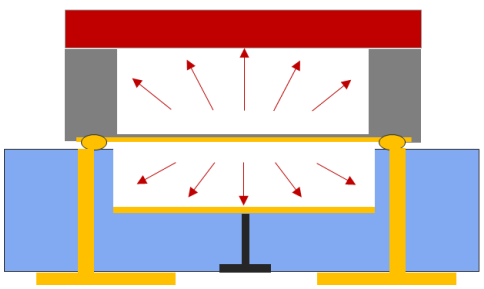
Cost-effective housing for IR emitters (KHIS)

APPLICATION

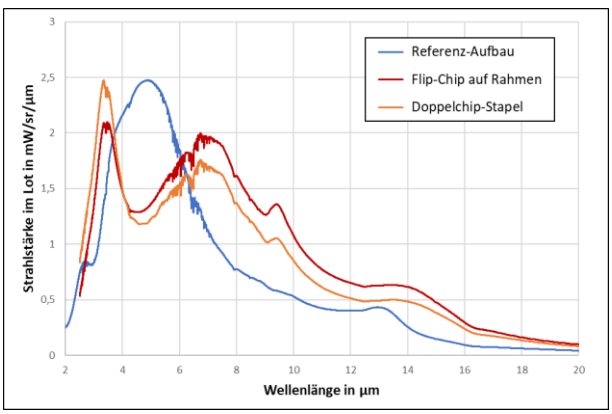
In the case of MEMS IR emitters, the package must fulfill several essential functions, such as sealing, optical filtering or windows, heat dissipation, and easy integration into circuits and electronic sensor systems.

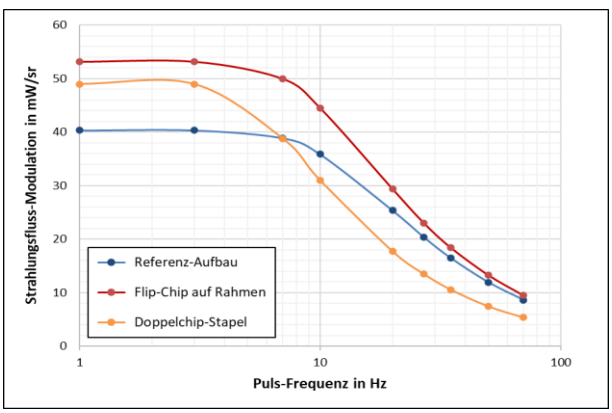
A novel, scalable housing platform for MEMS IR emitters enables the creation of SMD-compatible packages on both conventional FR4 circuit board material and ceramic substrates (LTCC). The layout can be flexibly adapted to accommodate various chip sizes.

DEMONSTRATORS



SPECTRUM AND DYNAMICS ON LTCC SUBSTRATES





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